		Board Cutout	
•			•
	Vendor logo, date code, RoHS (placed on top).		



	STACKUP	AND LA	AYEF	R DES	CRIPTI	ON		
GERBER LAYER NAMES:  GTP Top solder paste	<b>TH via</b> Top-Bot					ELECTRICAL LAYERS: Top: Signal/PWR/GND  Bottom: PWR/Signal/GND  ADDITIONAL LAYERS:  Mechanical 1: Board cutout ASM TOP: Assembly top ASM BOT: Assembly bottom Mechanical 13: Component 3D body Notes: Board shape and frame		
GTO Silkscreen					ELEC			
GTS Soldermask (halogen free) GTL 0.5oz+plating								
Core  GBL 0.5oz+plating  CDC Soldermask	hicknes: 1mm +/- 10%. Via type #1 0.3mm drill 0.6mm ring							Bott
GBS Soldermask (halogen free) GBO Silkscreen								
GBP Bottom solder paste  Total PCB thic								n drill n ring f
	VER	Y IMPO	RTA	NT NO	DTES			
GENERAL PCB SPECS					ADDITIONAL REQUIREMENTS			
Minimum copper to copper spacing	0.2mm (7.87mil)			● Electrical test : 100 % netlist.				
Minimum track width	0.2mm (7.87mil)							
PCB thickness	1mm +/-10%			<ul> <li>Boards are to be individually bagged.</li> </ul>				
PCB material	FR-4			PCB vendor to silkscreen UL and RoHS compliance marks, vendor  • logo and date code on top where shown (ignore if none of the				
Copper weight	External layer	1oz		info will be placed on PCB)				
	Internal layer -			Assembly note: Assembly house MUST provide notes in paper with shipped board if there were any changes during assembly and the board is not assembled 100% according to BOM and P&P files.  Note example:  Initial BOM   Current   Comment				
	BLUE							
Solder mask	Both sides							
	_			Part R1 IC5	FIT FIT	PCB status  NF NF		
	Glossy finish (NOT matte)						Not mounted due to bad footprint Not mounted due to part shortage	
	White epoxy ink		$\rightarrow$				Thou modified data to part shortage	
Silkscreen	Only top		-	SODIMM pads (top and bott micro inches nickel platic			tom) – 30 micro inches of gold over 50	
			$\rightarrow$		THEHES HICKEI	. pracing		
	No silkscreen on pads							
	Plated 🔀	Non-plated						
Hole types on the PCB and information	<ul> <li>Hole diameters are final</li> <li>manufactured diameters INCLUDII</li> <li>HOLE METALIZATION.</li> </ul>		DING					
Route process	V-score	Tab route	X					
Route process	V-score and tab route							
Panel	Yes	No	X					
	HASL lead free							
	HASL with lead							
Surface finish	Immersion gold		X					
	OSP							
	Hard gold Refer to additional requirements							